

Zenith

The Industry's Best Selling and First True 3D AOI Solution

Using patented True 3D technology, the Zenith measures true profilometric component shapes including foreign materials, patterns, and solder joints with True 3D capabilities to overcome inspection challenges.

ZENITH

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KOHYOUNG

Ultimate Solution for Inspection Challenges

Incomparable True 3D Inspection Performance

IPC-based Solder Joint Inspection

Al-powered Auto Programming (KAP)

AI

KSMART

KSMART Solutions: True 3D Measurement-based Process Control System

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Ultimate Solution for Inspection Challenges

 Circuit boards are becoming more complex with new products. An AOI machine is becoming even more crucial to the electronics manufacturing lines. The industry has many 2D, 2.5D and pseudo-3D inspection options that only compound issues with false calls and escapes. The Zenith AOI Series is the only machine that delivers True 3D Inspection to address solutions caused by highly specular packages and shadows from adjacent parts.





Incomparable True 3D Inspection Performance

- The Zenith AOI Series is the only solution in the industry to base its inspection criteria according to IPC-610 standards for electronic assembly acceptability requirements. It provides clear and concise AOI measurements to accurately identify multiple defects. Because it uses a quantitative True 3D measurement-based approach, the system delivers exceptional accuracy and repeatability.
- **True 3D Inspection Performance :** Missing Solder, Offset, Polarity, Upside Down, OCV/OCR, Solder Fillet, Billboarding, Lifted Lead, Lifted Body, Tombstone, Bridging, and more.





IPC-based Solder Joint Inspection

 Through Koh Youngs's proprietary vision algorithms, the Zenith series can quantify the exact height of a solder joint. Despite shadows or interreflection challenges, the Zenith accurately inspects and measures according to IPC-610 standards for electronic assembly acceptability requirements.





AI-powered Auto Programming (KAP)

 Industry-leading 3D profilometry technology converges with Koh Young's proprietary AI technology to deliver true automatic programming. The innovative geometry-based Koh Young Auto Programming (KAP) software solution reduces the programming process to minimizes time to production and reduces costs.



One Click Needed To Start KAP



Programming Time Saved by 70%

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KSMART Solutions: True 3D Measurement-based Process Control System

- Koh Young pioneered True 3D measurement technology 20 years ago to create a zero-defect future. This gave
 rise to KSMART Solutions and its continuous efforts to leverage data and connectivity.
- KSMART Solutions uses Artificial Intelligence to help automate process control while focusing on data management, analysis, and optimization. It collects data from across the factory line for defect detection, realtime optimization, enhanced decisions, and traceability to improve metrics, increase quality, and lower costs by eliminating variance, false calls, and escapes.

"KSMART Solutions is the Gateway to a Smart Factory"

- Converts data into knowledge for effective and quality-driven actions
- Delivers an AI-powered process analysis and optimization tool
- Achieves an autonomous process optimization facility



with the Koh Young AOI. Once you set it up the way you want, it runs like a dream. With SPI at the beginning of the line and an AOI at the end, we have a closed loop system." - Mid-tier ODM SMT Manager

Must-check Requirements of a 3D AOI System

	Re	quirements		Solutions					
	Solution	to Shadow Proble	em	3D Shadow Free Moiré Technology & 8-Way Projection					
	Specula	Problem Solutio	n						
	Shadowed Area	Between Tall Con	nponents						
	Small (01005 ir	n) Component Ins	pection	Multi-Frequency Moiré Technology					
		ement Range & Ac nent Range Proble							
	Real-time PC	B Warp Compens	sation W	Warp Compensation (Pad Referencing + Multi-Frequency Moiré Technology)					
Dar	k Component & W	hite Body Compo	onent Location						
	Component Body,	Lead Coplanarity	Inspection						
	Solder Joi	nt Profile Inspect	ion	True 3D Measurement					
	3D Po	larity Inspection							
	Compone	ent Crack Inspecti	on						
Inspection Items	Inspection Task		Missing, Offset, Rotation, 3D Polarity, Upside Down, OCV/VCR, Coplanarity, Solder Fillet, Lifted Lead, Billboarding, Tombstone, Bridging, Dimension						
Zenith Inspection Performance	Camera & Resolution	FOV Size	Full 3D Inspection Speed	Max. Measurement Height	Height Accuracy (KY Calibration Target)	Illumination			
	4M 10um	20 x 20 mm	7.1 cm ² /sec (0.56 sec/FOV)		±3%	IR-RGB LED (Dome Styled Illumination			
	4M 15um	30 x 30 mm	15.25 cm ² /sec (0.59 sec/FOV)	5 mm					
	4M 20um	40 x 40 mm	26.2 cm ² /sec (0.61 sec/FOV)						
PCB Handling	Conveyor Width Adjustment		Automatic						
	Conveyor Fix Type		Front / Rear Fixed (Factory setting)						
	(Optional Built-In Flipper) Machine Size		PCB Size (X*Y)	PCB Thickness	Clearance (Top / Bottor	n) Max. PCB Weigh			
	1000 x 1600 x 1627 mm (39.4 x 63.0 x 64.1 in)		Max: 500 x 500 mm (19.7 x 19.7 i Min: 100 x 100 mm (3.9 x 3.9 in)	n) 1.0 ~ 5 mm (0.04 ~ 0.2 in)	Clearance: 40 mm / 50 mm (1.6 x 2.0 Edge Clearance: 3 mm / 3 mm (0.1 x 0.1 ir	(4.4 lbs)			
Software	Supported Input Format		GERBER Data (274X, 274D), ODB++, Placement File, Mounter JOB File, Allegro, Zuken, Mentor (Optional)						
	Programing Software		ePM-AOI, AOI GUI						
	Statistical Process Control Tool		SPC Plus, Review Station						
	User-Friendly Operator		Library Manager & KYCAL (Auto Camera Calibration, Auto Illumination Calibration, Auto Height Calibration)						
	Operating System		WINDOWS 10 IOT ENTERPRISE LTSC 2019						
Add-On Solutions						note Access, Offline nk Data Analysis, Notificatio			

- Foreign Material Inspection

(PCB Height 950mm)

Height

PCB 1

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(The above specifications are subject to change without notice.)

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	Single Lane	Dual Lane	Single Lane	Dual Lane	Single Lane	Dual Lane			
	330 x 330 mm (12.9 x 12.9 in)	Single Mode °	510 x 510 mm (20.0 x 20.0 in)	Single Mode °	850 x 690 mm (33.4 x 27.1 in)	Single Mode			
Max. PCB Size		330 x 580 mm (12.9 x 22.8 in)		510 x 580 mm (20.0 x 22.8 in)		850 x 580 mm (33.4 x 22.8 in)			
(X × Y)		Dual Mode		Dual Mode		Dual Mode			
		330 x 325.5 mm (12.9 x 12.8 in)		510 x 320 mm (20.0 x 12.5 in)		850 x 320 mm (33.4 x 12.5 in)			
Min. PCB Size		50 x 50 mm	70 x 70 mm (2.7x2.7 in)						
PCB Thickness	0.4 ~ 4 mm ((0.01 ~ 0.15 in)	0.4 ~ 5 mm (0.01 ~ 0.19 in)		0.6 ~ 8 mm (0.02 ~ 0.31 in)				
Max. PCB Weight	Standard : 2kg	g (4.4 lbs), Heavy	: 5kg (11.0 lbs)	10kg (22.0 lbs)					
Machine Weight	550 kg (1212.5 lbs)	600 kg (1322.7 lbs)	600 kg (1322.7 lbs)	700 kg (1543.2 lbs)	850 kg (1873.9 lbs)	900 kg (1984.1 lbs)			
Bottom Clearance	50 mm (1.9 in)								
Supplies	220 VAC ± 10%, 1 Phase, 50/60Hz, 5Kgf/cm² (0.45MPa)								
W	820 mm (32.2 in)		1000 mm (39.3 in)		1350 mm (53.1 in)				
D	1265 mm (49.8 in) 1445 mm (56.8 in)		1265 mm (49.8 in)	1445 mm (56.8 in)	1445 mm (56.8 in)				
н	1627 mm (64.0 in)								

° Please contact us for more information about PCB Sizes. (The above specifications are subject to change without notice.)



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